

WAFER PROCESSING METHOD

ABSTRACT OF THE DISCLOSURE

A wafer processing method includes a polyester
5 sheet providing step of positioning a wafer in an inside
opening of a ring frame and providing a polyester sheet
on a back side of the wafer and on a back side of the
ring frame, a uniting step of heating the polyester sheet
as applying a pressure to the polyester sheet to thereby
10 unite the wafer and the ring frame through the polyester
sheet by thermocompression bonding, a dividing step of
cutting the wafer by using a cutting apparatus to thereby
divide the wafer into individual device chips, and a
pickup step of heating the polyester sheet, pushing up
15 each device chip through the polyester sheet, and then
picking up each device chip from the polyester sheet.

FIGURE 4